

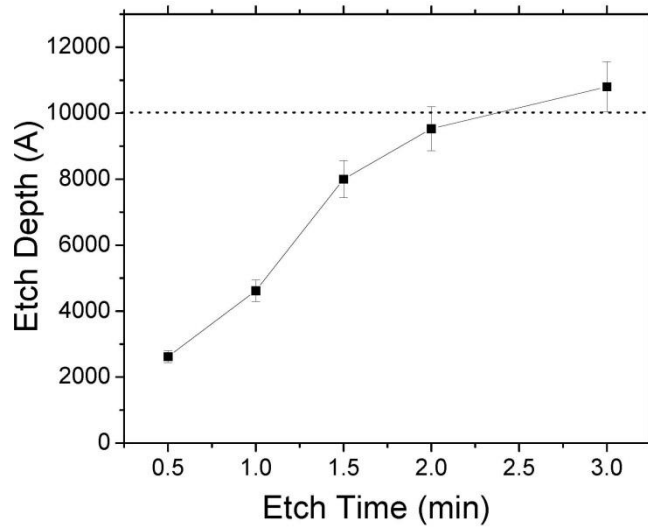
Aluminum Etching

Panasonic 1, Micron-scale
features

Mask : Resist

Chiou-Fu Wang

Structure : 10nm Ti / 1um Al / Si substrate



ICP recipe

$\text{BCl}_3 / \text{Cl}_2 = 20 / 40$ sccm

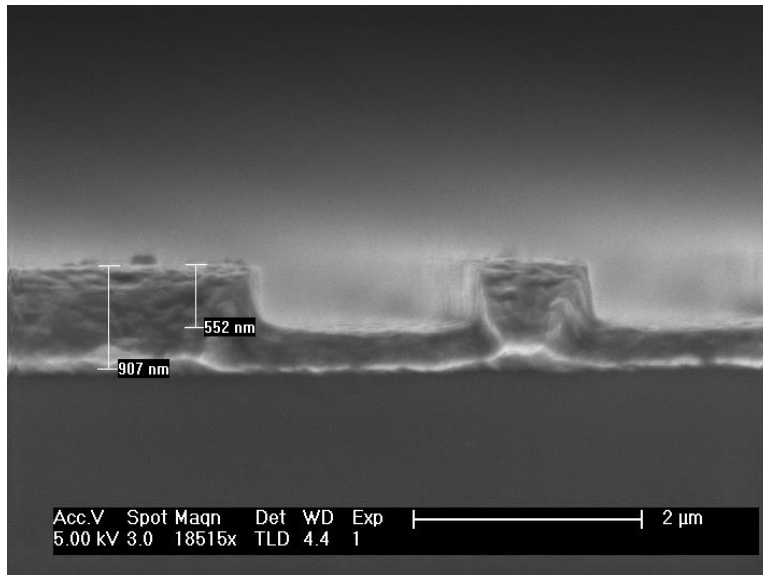
Pressure = 0.7Pa

ICP Power = 300W

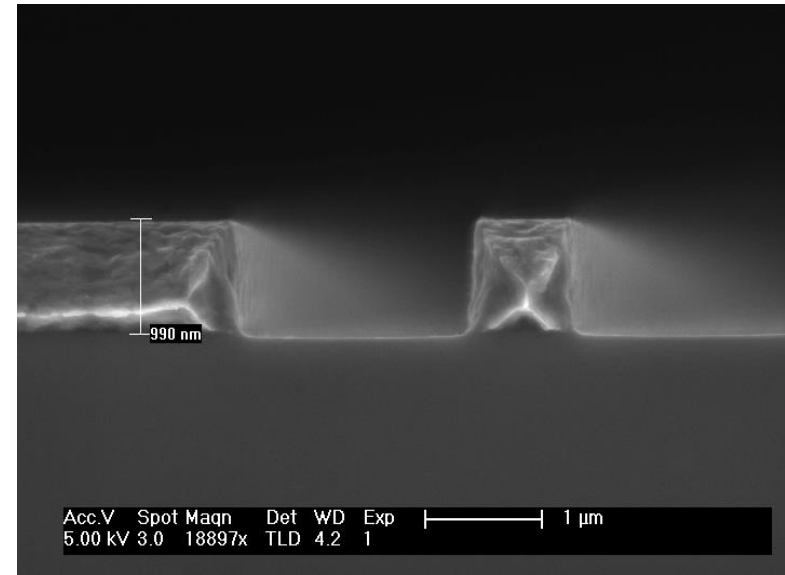
Bias Power = 70W

Immediately Rinse in DI water upon removal

Deep Sub-um and nanoscale features show undercut profiles



1 min



2 min